



# **Intel® Firmware Support Package (Intel® FSP) for Intel Atom® x6000E Series, and Intel® Pentium® and Celeron® N and J Series Processors (*Formerly known as Elkhart Lake*), MR3**

**Release Notes**

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***March 2022***



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## Revision History

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These are the main releases of Intel® Firmware Support Package (Intel® FSP) for Intel® Soc processor Code-Named Elkhart Lake.

Date	Revision	Description
April 2020	Alpha (3)	Initial Release (Elkhart Lake label v2115_00_423)
September 2020	Beta (2)	Beta release (Elkhart Lake label v2341_05_33)
October 2020	Beta (3)	Beta 3 release (ElkhartLake_Daily2411_00_215)
December 2020	Beta (4)	Beta 4 release (ElkhartLake_Label2463_00_122)
March 2021	PV	PV Release (ElkhartLake_Label3092_03_101)
March 2021	Fusa PV	PV Release (ElkhartLake_Label3125_02_104)
April 2021	PR1	PR1 Release (ElkhartLake_Label3162_01_105)
August 2021	MR1	MR1 Release (ElkhartLake_Label3273_04_122)
November 2021	MR2	MR2 Release (ElkhartLake_Label3432_03_138)
March 2022	MR3	MR3 Release (ElkhartLake_Label4072_03_162)

## 1.0 Introduction

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This package contains required binary image(s) and collateral for the Intel® Firmware Support Package (Intel® FSP) for Intel® Soc processor code-named Elkhart Lake.

Compliant with FSP 2.1 External Architecture Specification.

This document provides system requirements, installation instructions, issues and limitations, and legal information.

To learn more about this product, see:

- New and previously new features listed in [Section 2.0, New in This Release](#).
- Reference documentation listed in [Section 1.2, Related Documentation, Tools, and Packages](#).

The following table lists the relevant platform software components used during development and validation of this release.

**Table 1. Platform Software Component Information**

Please use the correct microcode when integrating Intel® FSP. Any processor that does not have the correct microcode update loaded is considered to be operating out of specification. See the relevant bootloader's release notes for more details regarding microcode loading.

Supported Silicon Stepping	Microcode Version
B0	m_01_90661_00000016

## 1.1 Terminology

The following terms are used in this document.

**Table 2. Terminology**

Term	Description
API	Application Programming Interface
BSF	Binary Settings File
BCT	Binary Configuration Tool
CRB	Customer Reference Board

Term	Description
Intel® EDC	Intel® Embedded Design Center
Intel® FSP	Intel® Firmware Support Package
SoC	System on Chip

## 1.2 Related Documentation, Tools, and Packages

**Table 3. Related Documentation, Tools, and Packages**

Document	Location
<i>ElkhartLake_FSP_Integration_Guide.pdf</i>	Available in this release package
<i>Intel® Binary Configuration Tool for Intel® Firmware Support Package</i>	<a href="http://www.intel.com/fsp">www.intel.com/fsp</a>
<i>Intel® Firmware Support Package (Intel® FSP) External Architecture Specification (EAS) v2.1</i>	<a href="https://cdrdv2.intel.com/v1/dl/getContent/611786">https://cdrdv2.intel.com/v1/dl/getContent/611786</a>

## 1.3 Intended Audience

The intended audience is platform and system developers who intend to use an Intel® FSP-based boot loader for the firmware solution for their overall design based on the Intel® SOC processor code-named Elkhart Lake. This group includes, but is not limited to, system BIOS developers, boot loader developers, and system integrators.

## 1.4 Customer Support

Intel offers support for this software at the API level only, defined in the Intel® FSP Integration Guide and reference manuals listed in [Section 1.2, Related Documentation, Tools, and Packages](#).

For technical support, please raise IPS (Intel® Premier Support) at <https://intel.my.salesforce.com/>

## **2.0**      *New in This Release*

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### **2.1**      **MR3 Features**

- Adopting Elkhart Lake IAFW external release ElkhartLake Label 4072\_03\_162

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## 3.0 *Fixed Issues*

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The following list contains the fixed issues in this release:

- None.

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## **4.0**      *Limitations*

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### **4.1**      **Current Release**

- None.

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## **5.0**      ***Known Issues***

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### **5.1**      **Current Release**

- None.

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## 6.0 Split FSP image into individual FSP-T/M/S component

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FSP 2.1 image can be split to 3 individual components using the SplitFspBin.py script in release package. For further details on splitting and integrating FSP, please refer the relevant bootloader's release notes.

### **Rebase address:**

Bootloader will rebase and relocate FSP binary dynamically, so the base address is not hardcoded with the default base address and location. Once configure the FSP binary as XIP, Bootloader can decide where the binary will be placed in the core boot's CBFS or SBL's Fv and will take care of rebasing it during build.

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## 7.0 *Where to Find the Release*

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This package can be found from the **Elkhart Lake Firmware Best Known Configuration (BKC)** searchable at Intel® Resource & Design Center (RDC) Software Kits:  
<https://www.intel.com/content/www/us/en/secure/design/confidential/software-kits/view-all.html?s=Newest>

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## **8.0      Release Content**

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This release contains:

- Intel® FSP Integration Guide
- Intel® FSP Binary
- Binary Settings File (BSF)
- Release Notes

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## 9.0 Hardware and Software Compatibility

### 9.1 Supported Hardware

This Intel® Firmware Support Package (Intel® FSP) release is specifically targeted for Intel Atom® x6000E series, and Intel® Pentium® and Celeron® N and J Series processors (Formerly known as Elkhart Lake).

### 9.2 Supported Bootloaders

This release can be installed on either a Windows\* or a Linux\* system. However, the Intel® FSP binary itself can be used with any software development environment to generate a complete boot loader solution.

The software in this release has been validated on customer reference boards (CRBs) with the boot loader and operating systems listed in the following table.

**Table 4. Operating System/Boot Loader Support**

Product Family	Boot Loader	Operating System
Intel® Soc Processor code-named Elkhart Lake	EHL SBL* with the UEFI/OsLoader payload	Yocto Project* Windows 10
Intel® Soc Processor code-named Elkhart Lake	coreboot* with the UEFI payload	Yocto Project* Windows 10

## 10.0 Source code level FSP UPD values configuration

FSP UPD settings can be configured from respective bootloaders from source code level. Details provided here for modifying default values provided by FSP UPDs in supported bootloaders as mentioned in Section 9.2.

Here are 2 potions of FSP that can be changed from bootloaders:

FSP potion	FSP Headers file (UPD reference codes)
FSP-M	Include/ <b>FspmUpd.h</b>
FSP-S	Include/ <b>FspsUpd.h</b>

The respective UPDs can be found inside the respective FSP headers file.

### 10.1 coreboot

To modify the default FSP UPD values in coreboot, please navigate to respective files:

FSP potion to change	Source code
FSP-M	src\soc\intel\elkhartlake_dev\romstage\ <b>fsp_params.c</b>
FSP-S	src\soc\intel\elkhartlake_dev\ <b>fsp_params.c</b>

Here are the **examples** to change the UPD values: -

- For UPDs that have been exposed in the source code, just change the value (highlighted in yellow) to the desired value:

```
/* Vt-D config */
m_cfg->VtdDisable = 0;
```

- For UPDs that have not been exposed in coreboot source code, just insert code as shown below:

<b>FSP-M</b> (insert code below in this function: <b>void platform_fsp_memory_init_params_c b(FSPM_UPD *mupd, uint32_t version)</b> )	<b>FSP-S</b> (insert code below in this function: <b>void platform_fsp_silicon_init_params_c b(FSPS_UPD *supd)</b> )
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m_cfg-> {UPD} = {desired value}	params-> {UPD} = {desired value}
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## 10.2 Slim Bootloader

To modify the default FSP UPD values in slim bootloader, please navigate to respective files:

FSP potion to change	Source code
FSP-M	SblInternal\Platform\ElkhartlakeBoardPkg\Library\Stage1BBoardInitLib\Stage1BBoardInitLib.c
FSP-S	SblInternal\Platform\ElkhartlakeBoardPkg\Library\Stage2BoardInitLib\Stage2BoardInitLib.c

Here are the **examples** to change the UPD values: -

- For UPDs that have been exposed in the source code, just change the value (highlighted in yellow) to the desired value:

```
/* Vt-D config */
```

```
Fspmcfg->VtdDisable = 0;
```

- For UPDs that have not been exposed in slimboot source code, just insert code as shown below:

<b>FSP-M</b> (insert code below in this function: <code>VOID UpdateFspConfig (VOID *FspmUpdPtr)</code> )	<b>FSP-S</b> (insert code below in this function: <code>VOID UpdateFspConfig (VOID *FspUpdPtr)</code> )
Fspmcfg-> {UPD} = {desired value}	Fspscfg-> {UPD} = {desired value}